

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q84452

Michel PUECH

Appln. No.: 10/516,455

Group Art Unit: 1763

Confirmation No.: 2876

Examiner: Allan W. OLSEN

Filed: December 3, 2004

For: METHOD AND DEVICE FOR SUBSTRATE ETCHING WITH VERY HIGH POWER  
INDUCTIVELY COUPLED PLASMA

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of three months, extending the time for responding to the Office Action of August 15, 2007 to February 15, 2008.

The statutory fee of \$1,050.00 is being charged to Deposit Account No. 19 4880 via EFS Payment Screen. The USPTO is also directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

/Dion R. Ferguson/

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

Dion R. Ferguson  
Registration No. 59,561

WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: February 15, 2008